



**Glass cloth base epoxy resin
Flame retardant copper clad laminate**

NPG-150DR

■ FEATURES

- Halogen, antimony, and red phosphorous free
- Flammability meets UL 94V-0
- Excellent thermal resistance and reliability
- U.L file number E98983
- Excellent CAF resistance (Anti-migration)
- UV blocking type
- IPC-4101E L127/128

■ PERFORMANCE LIST

Characteristics	Unit	Condition	Typical Values	SPEC	Test Method	
Volume resistivity	MΩ-cm	C-96/35/90	5 x10 ⁸ ~ 5x10 ⁹	10 ⁶ ↑	2.5.17	
Surface resistivity	MΩ	C-96/35/90	5 x10 ⁶ ~ 5x10 ⁷	10 ⁴ ↑	2.5.17	
Permittivity 1GHz	-	C-24/23/50	4.4-4.5	-	2.5.5.9	
Loss Tangent 1GHz	-	D-24/23/50	0.008-0.009	-	2.5.5.9	
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1	
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6	
Moisture absorption	%	D-24/23	0.05-0.10	0.8 ↓	2.6.2.1	
Flammability	-	C-48/23/50	V-0	V-0	UL94	
Peel strength 1 oz (≥0.5mm)	lb/in	288°Cx10" solder floating	8-9	6 ↑	2.4.8	
Thermal stress	SEC	288°C solder dipping	300 ↑	10 ↑	2.4.13.1	
Pressure cooker (2 atm 120°C)	1/2 hr	SEC	288°C dipping	300 ↑	N/A	-
	1 hr	SEC	288°C dipping	300 ↑	N/A	-
	2 hrs	SEC	288°C dipping	300 ↑	N/A	-
Flexural strength	LW	N/mm ²	A	460-510	415 ↑	2.4.4
	CW	N/mm ²	A	430-460	345 ↑	2.4.4
Dimensional stability X-Y axis	%	E-0.5/170	0.01-0.03	0.05 ↓	2.4.39	
Coefficient of thermal expansion						
X-Y axis	ppm/°C	TMA	11-14	N/A	2.4.24	
Z-axis before Tg	ppm/°C	TMA	30-40			
Z-axis after Tg	ppm/°C	TMA	230-250			
Glass transition temp	°C	TMA	150	N/A	2.4.24	
Decomposition temperature (Td 5% W/L)	°C	TGA	380	N/A	2.4.24.6	

NOTE:

The average value in the table refers to samples of .062" 1/1.
Test method per IPC-TM-650

Data shown are nominal values for reference only.



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NPG-150DTL

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Characteristics	Unit	Condition	Typical Values	SPEC	Test Method
Volume resistivity	MΩ-cm	C-96/35/90	5.0 x10 ⁹	10 ⁶ ↑	2.5.17
Surface resistivity	MΩ	C-96/35/90	5.0 x10 ⁷	10 ⁴ ↑	2.5.17
Permittivity 1 GHz	-	C-24/23/50	3.8-4.1	-	2.5.5.9
Loss Tangent 1 GHz	-	C-24/23/50	0.010-0.011	-	2.5.5.9
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption	%	D-24/23	0.20-0.30	0.8 ↓	2.6.2.1
Flammability	-	C-48/23/50	V-0	V-0	UL94
Peel strength 1 oz (≥0.5mm)	lb/in	288°C x10" solder floating	8-9	6 ↑	2.4.8
Thermal stress	SEC	288°C solder dipping	300 ↑	10 ↑	2.4.13.1
Glass transition temp	°C	TMA	150	N/A	2.4.24
Dimensional stability X-Y axis	%	E-4/105	0.01-0.03	0.05 ↓	2.4.39
Coefficient of thermal expansion					
X-Y axis	ppm/°C	TMA	11-14	N/A	2.4.24
Z-axis before Tg	ppm/°C	TMA	30-40		
Z-axis after Tg	ppm/°C	TMA	230-250		
Decomposition temperature (Td 5% W/L)	°C	TGA	380	N/A	2.4.24.6

NOTE:

The average value in the table refers to samples of .020" 1/1.

Test method per IPC-TM-650

Data shown are nominal values for reference only.



■ **CONSTRUCTION**

THICKNESS		CONSTRUCTION		THICKNESS		CONSTRUCTION	
mm	mil			mm	mil		
0.05 sp	2	1067	1 ply	0.45 sp	18	1506	3 plies
0.08 1p	3	1086	1 ply	0.50	20	7628	3 plies
0.10	4	1080	2 plies	0.53	21	7628	3 plies
0.11	4	2116	1 ply	0.60	24	7628	3 plies
0.13 sp	5	2116	1 ply	0.77	30	7628	4 plies
0.15	6	1506	1 ply	0.8	31.5	7628	4 plies
0.21	8	7628	1 ply	0.9	36	7628	5 plies
0.26	10	2116	2 plies	1.0	39	7628	5 plies
0.30	12	1506	2 plies	0.9	36	7628	5 plies
0.35	14	7628	2 plies	1.1	43	7628	6 plies
0.38	15	7628	2 plies	1.2	47	7628	6 plies

Requirement for not listed glass fabrics types, please contact our technical customer service team for discussion in advance.

■ **PRODUCT SIZE & THICKNESS**

THICKNESS inch (mm)	COPPER CLADDING oz (µm)	SIZE		THICKNESS TOLERANCE
		inch	mm	
0.002 (0.05)	T (12)	48.8 x 36.6	1240 x 0930	IPC-4101E SPEC CLASS C/M
to	to	48.8 x 40.5	1240 x 1030	
0.047 (1.2)	3.0 (102)	48.8 x 42.5	1240 x 1080	

■ **Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.**

■ **Grain direction is shown on the certificate of conformance.**



**Glass cloth base epoxy resin
 Flame retardant prepreg**

NPG-150DB

■ FEATURES

- Rheology of resin controlled to benefit the lamination of the boards.
- Modified phosphorous epoxy provides excellent heat and chemical resistance.
- Other properties are similar to standard FR-4.

■ PERFORMANCE LIST

Specification: IPC-4101E is applicable.
 Data shown are nominal values for reference only.

Glass style	RC%	GT sec (171°C)	VC%
1027	72 ± 3	130 ± 20	1.5 ↓
1027MR	74 ± 3		
1027HR	76 ± 3		
106 1037	72 ± 3		
106MR 1037MR	74 ± 3		
106HR 1037HR	76 ± 3		
1067	70 ± 3		
1067MR	74 ± 3		
1067HR	76 ± 3		
1078	64 ± 3		
1078MR	67 ± 3		
1078HR	70 ± 3		
1080	64 ± 3		
1080MR	67 ± 3		
1080HR	70 ± 3		
2112	62 ± 3		
2113	58 ± 3		
2116	52 ± 3		
2116MR	56 ± 3		
2116HR	60 ± 3		
1506	50 ± 3		
1506MR	54 ± 3		
7628	45 ± 3		
7628MR	49 ± 3		
7628HR	52 ± 3		



■ **After Pressed Theoretical Thickness of prepreg (per ply)**

Data shown are nominal values for reference only.

Copper thickness of inner layer Hoz / 1oz

Type	RC	Press Thk Per Ply						
		Hoz Cu (um)				1oz Cu (um)		
		100%	70%	50%	30%	70%	50%	30%
1027	72%	41	36	32	29	30	23	16
1027MR	74%	45	39	36	33	34	27	20
1027HR	76%	49	44	40	37	38	31	24
106/1037	72%	52	47	43	40	41	34	27
106MR/1037MR	74%	56	51	48	44	46	39	32
106HR/1037HR	76%	62	56	53	50	51	44	37
1067	70%	60	55	51	48	49	42	35
1067MR	74%	70	65	62	58	60	53	46
1067HR	76%	77	72	68	65	66	59	52
1078	64%	77	72	69	65	67	60	53
1078MR	67%	86	81	77	74	75	68	61
1078HR	70%	96	91	87	84	85	78	71
1080	64%	77	72	69	65	67	60	53
1080MR	67%	86	81	77	74	75	68	61
1080HR	70%	96	91	87	84	85	78	71
2112	62%	107	102	99	95	97	90	83
2113	58%	104	99	96	93	94	87	80
2116	52%	119	114	111	107	109	102	95
2116MR	56%	133	128	124	121	122	115	108
2116HR	60%	141	136	132	129	130	123	116
1506	50%	175	170	166	163	164	157	150
1506MR	54%	194	189	186	182	184	177	170
7628	45%	198	193	190	187	188	181	174
7628MR	49%	219	214	210	207	208	201	194
7628HR	52%	236	231	228	224	226	219	212

1. Due to the pressed thickness could be effected by press related condition, the table showed for reference only.

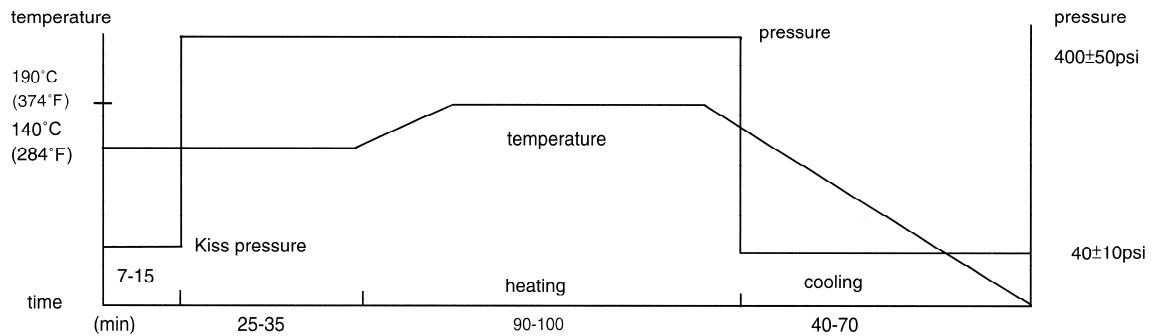
2. The glass cloth minimum thickness customer must be concerned

■ **Storage Condition: 23°C RH50% ↓, for 3 months**

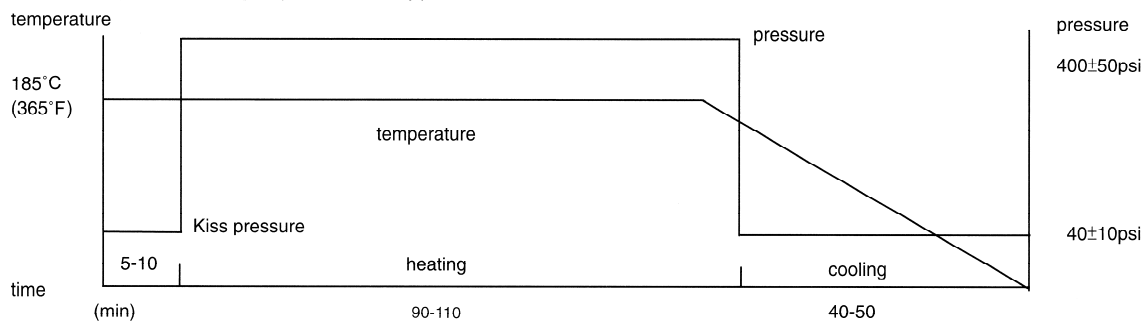


Recommended press cycles:

A:2T2P(2 temperature step/2 pressure step)



B:1T2P(1 temperature step/2 pressure step)



Suggestions:

1. Heating rate of material between 70°C(158°F) and 140°C(284°F).
 1~3°C/min (1.8~5.4°F/min) is acceptable.
 1.5~2.5°C/min (2.7~4.5°F/min) would be better.
2. Temperature of material over 170°C(338°F) must be held for at least 60 min to allow resin to fully cure.
3. The pressure should be kept below 100psi during cooling to ambient temperature.
4. Cooling rate of material should be kept under 2.5°C/min (4.5°F/min) when the temperature of material is over 100°C(212°F), in order to avoid introducing twist.

■ CERTIFICATION UL

- UL File No.: E98983
- ANSI TYPE: FR-4.1
- UL 746 Recognition

Minimum Material Thickness inch (mm)	Clad cond. Thickness		Max. Area Diameter inch (mm)	Max. Operating Temp	Solder Lts Temp Time °C sec		UL 94 Flame Class
	Min. mils (µm)	Max. mils (µm)			Temp °C	Time sec	
0.0016 (0.04)	0.59 (15)	4.02 (102)	2.0 (50.8)	130	288	30	94V-0